

WHAT IS CLAIMED IS:

1. A circuit board for mounting a semiconductor chip, the circuit board including a semiconductor chip region for mounting the semiconductor chip and wiring regions in which wirings electrically connected to the semiconductor chip are formed, the circuit board comprising:
 - a reinforcement layer region in which reinforcement layers for maintaining the strength of the circuit board for mounting the semiconductor chip is formed; and
 - a protective film that covers the wirings;wherein the wiring regions are disposed in a vicinity of the semiconductor chip region and the reinforcement layer region is disposed in vicinity of the wiring regions.
2. The circuit board for mounting a semiconductor chip of claim 1, wherein the semiconductor chip covers part of the wiring regions.
3. The circuit board for mounting a semiconductor chip of claim 1, wherein the reinforcement layers are copper wirings.
4. The circuit board for mounting a semiconductor chip of claim 1, wherein the protective film is planarized.
5. The circuit board for mounting a semiconductor chip of claim 1, wherein a surface of the protective film is planarized by being cut and polished.

6. A method of manufacturing a circuit board for mounting a semiconductor chip, the circuit board including a semiconductor chip region for mounting the semiconductor chip, a reinforcement layer region in which reinforcement layers for maintaining the strength of the circuit board for mounting the semiconductor chip are formed, and wiring regions in which wirings electrically connected to the semiconductor chip are formed, the method comprising:

forming the wirings in the wiring regions disposed in a vicinity of the semiconductor chip region;

forming the reinforcement layers in the reinforcement layer region disposed in a vicinity of the wiring regions; and

forming a protective film that covers the wirings.

7. The manufacturing method of claim 6, further including a step of planarizing the protective film.

8. The manufacturing method of claim 7, wherein the planarization is carried out by cutting and polishing a surface of the protective film.

9. A circuit board for mounting a semiconductor chip, the circuit board comprising:

an insulating substrate, the insulating substrate having a top surface and a bottom surface, with the top surface including mutually separated first,

second and third regions;

wirings provided in the second regions on the top surface of the insulating substrate, with the semiconductor chip being electrically connected to the wirings;

reinforcement layers provided in the third region on the top surface of the insulating substrate, with the reinforcement layers maintaining the strength of the circuit board for mounting a semiconductor chip;

a protective film formed on the insulating substrate so as to cover the wirings and the reinforcement layers; and

the semiconductor chip mounted on the protective film above the first region on the top surface of the insulating substrate,

wherein the third region encloses the first region and the second regions.

10. The circuit board for mounting a semiconductor chip of claim 9, wherein the protective film is planarized.

11. The circuit board for mounting a semiconductor chip of claim 9, wherein the protective film is a solder resist.

12. The circuit board for mounting a semiconductor chip of claim 9, wherein the reinforcement layers comprise a metal.

13. The circuit board for mounting a semiconductor chip of claim 9, wherein

the reinforcement layers comprise conductive materials.

14. The circuit board for mounting a semiconductor chip of claim 9, wherein the reinforcement layers comprise insulating materials.

15. The circuit board for mounting a semiconductor chip of claim 9, further comprising solder balls that are disposed on the bottom surface of the insulating substrate and electrically connected to the wirings.